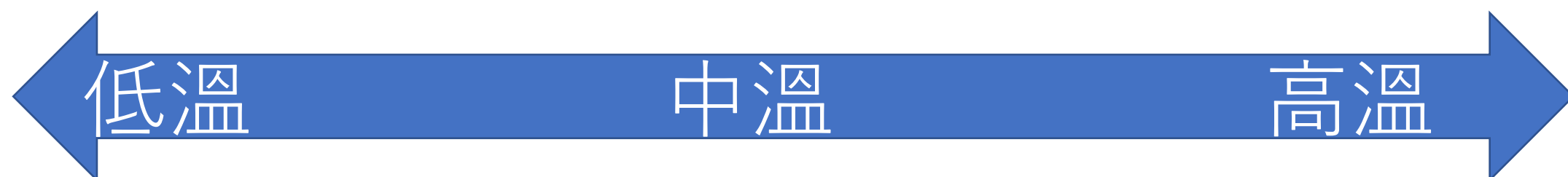


Negative Thermal Expansion Materials

較大的熱收縮，確保了在低溫到高溫的廣泛溫度範圍內,能夠實現零膨脹。



-10 ~ 80 °C

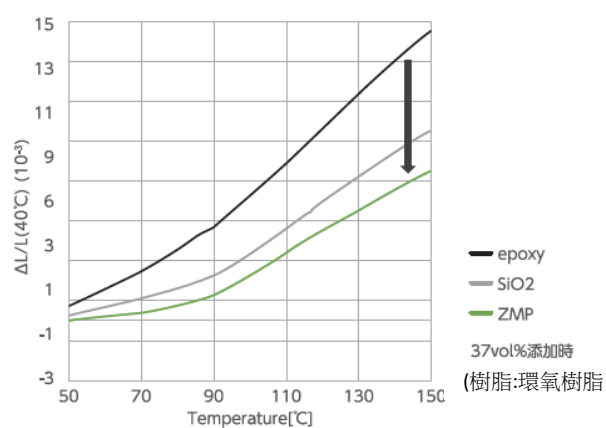
-170 ~ 230 °C

100 ~ 500 °C



ZMP

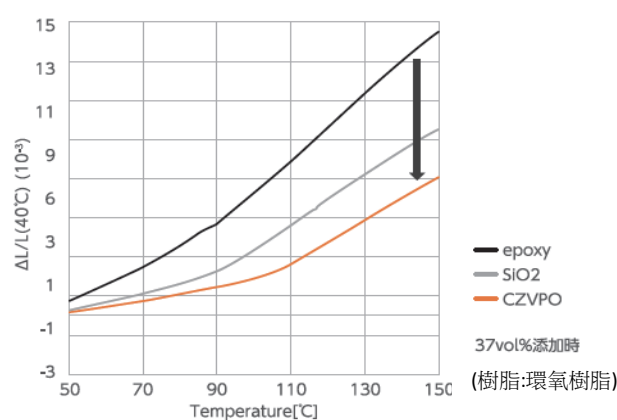
-66
ppm/K



D50:4~5μm

CZVPO

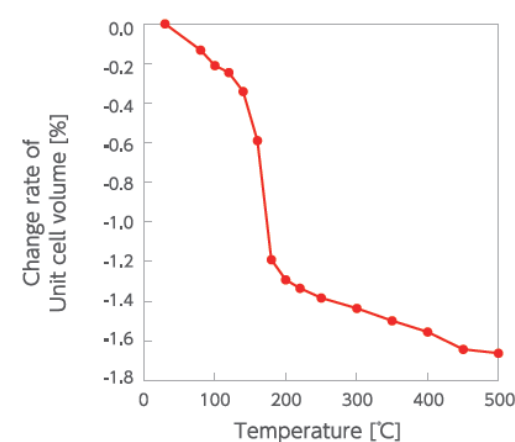
-12
ppm/K



D50:2~10μm

ZSP

-33
ppm/K



D50:0.6μm

【用途】：半導體的封裝材料,MUF,銅箔基板,感應器等

